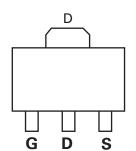
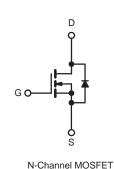


N-Channel 100 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY							
V _{DS} (V)	$R_{DS(on)}$ (Ω) Typ.	I _D (A) ^a	Q _g (Typ.)				
100	0.102 at V _{GS} = 10 V	4.2					
	0.120 at V _{GS} = 6 V	3.8	2.9 nC				
	0.125 at V _{GS} = 4.5 V	3.6					





FEATURES

- TrenchFET® Power MOSFET
- 100 % R_q and UIS Tested



APPLICATIONS

- DC/DC Converters / Boost Converters
- Load Switch
- LED Backlighting in LCD TVs
- · Power Management for Mobile Computing

ABSOLUTE MAXIMUM RATINGS (TA	_λ = 25 °C, unless otl	nerwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V_{GS}	± 20	·	
	T _C = 25 °C		4.2	
Continuous Drain Current (T _{.I} = 150 °C)	$T_C = 70 ^{\circ}C$	I _D	3.5	
Continuous Brain Current (1) = 100 °C)	T _A = 25 °C	טי	3.2 ^{b,c}	
	T _A = 70 °C		2.8 ^{b,c}	A
Pulsed Drain Current (t = 300 μs)		I _{DM}	15	
Continuous Source-Drain Diode Current	T _C = 25 °C	T _C = 25 °C	2.1	
Continuous Source-Dialit Diode Current	T _A = 25 °C	'S	1 ^{b, c}	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	3	
Single Pulse Avalanche Energy	L=0.11111	E _{AS}	0.45	mJ
	T _C = 25 °C		2.5	
Maximum Power Dissipation	$T_C = 70 ^{\circ}C$	P _D	1.6	w
Maximum r ower Dissipation	T _A = 25 °C	ט י	1.25 ^{b, c}	
	T _A = 70 °C		0.8 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	75	100	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	$R_{th,IF}$	40	50				

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 166 °C/W.

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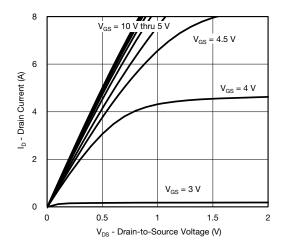
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			59		> //06
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 4.8		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2		3	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zana Oata Waltana Busha Oamaat	,	V _{DS} = 100 V, V _{GS} = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	5			Α
		$V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$		0.102		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 6 V, I _D = 1 A		0.120		Ω
	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	$V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$		0.125		1
Forward Transconductance ^a	9 _{fs}	V _{DS} = 20 V, I _D = 2 A	1	5		S
Dynamic ^b		<u>-</u>		<u> </u>	<u> </u>	
Input Capacitance	C _{iss}			196		
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		67		pF
Reverse Transfer Capacitance	C _{rss}			14		Pi
		V _{DS} = 50 V, V _{GS} = 10 V, I _D = 2.2 A		5.2	10.4	
Total Gate Charge	Q _g	D3 7 G3 - 7 D		2.9	5.8	nC
Gate-Source Charge	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 2.2 \text{ A}$		1		
Gate-Drain Charge	Q _{gd}			1.4		
Gate Resistance	R _g	f = 1 MHz	0.9	4.3	8.6	Ω
Turn-On Delay Time	t _{d(on)}			40	60	
Rise Time	t _r	$V_{DD} = 50 \text{ V}, R_1 = 27.7 \Omega$		68	102	- - -
Turn-Off Delay Time	t _{d(off)}	$I_D = 1.8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_a = 1 \Omega$		14	21	
Fall Time	t _f	3		20	30	
Turn-On Delay Time	t _{d(on)}			8	16	ns
Rise Time	t _r	$V_{DD} = 50 \text{ V}, R_1 = 27.7 \Omega$		10	20	1
Turn-Off Delay Time	t _{d(off)}	$I_D = 1.8 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		10	20	
Fall Time	t _f	 9		7	14	
Drain-Source Body Diode Characteristi	<u> </u>		<u> </u>	<u> </u>	<u> </u>	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.1	
Pulse Diode Forward Current ^a				1	- 8	Α
Body Diode Voltage	V _{SD}	I _S = 1.8 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}		<u> </u>	23	35	ns
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 1.8 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s},$		21	32	nC
Reverse Recovery Fall Time	t _a	$T_{\rm J} = 25 ^{\circ}{\rm C}$		17		ns
Reverse Recovery Rise Time	t _b	0		6		

Notes:

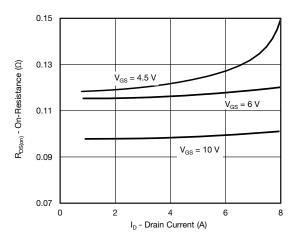
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

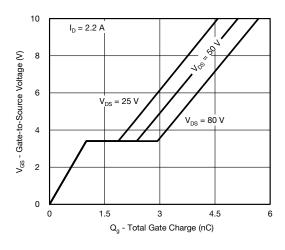




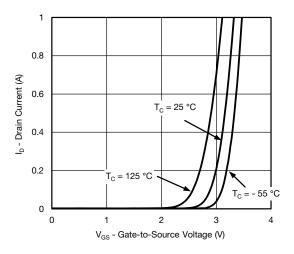
Output Characteristics



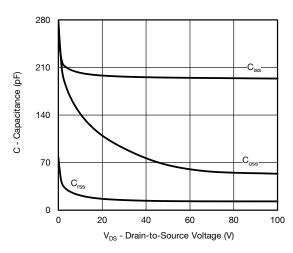
On-Resistance vs. Drain Current and Gate Voltage



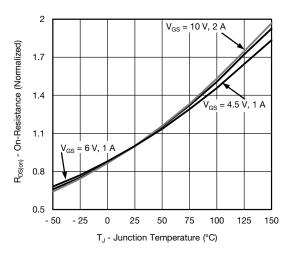
Gate Charge



Transfer Characteristics



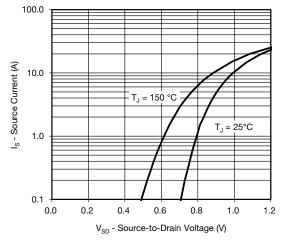
Capacitance



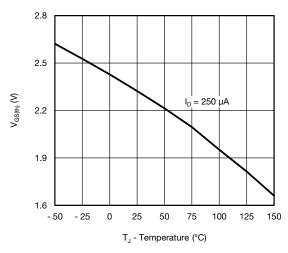
On-Resistance vs. Junction Temperature

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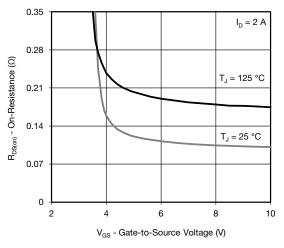




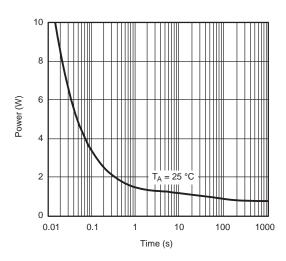
Source-Drain Diode Forward Voltage



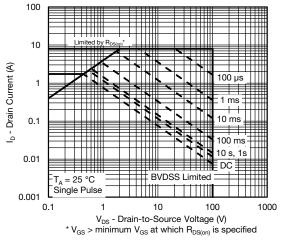
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



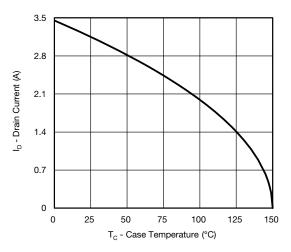
Single Pulse Power



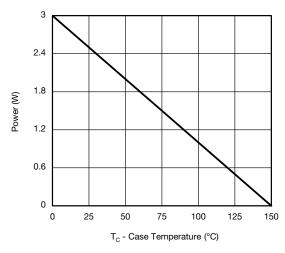
Safe Operating Area

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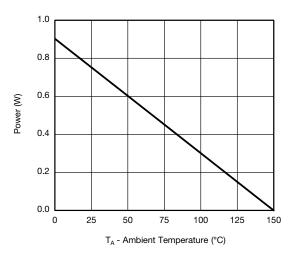




Current Derating*





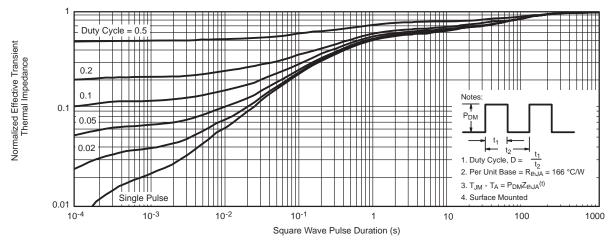


Power, Junction-to-Ambient

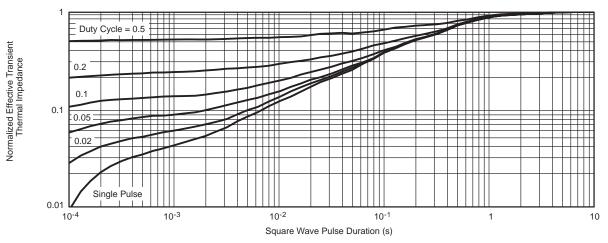
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^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

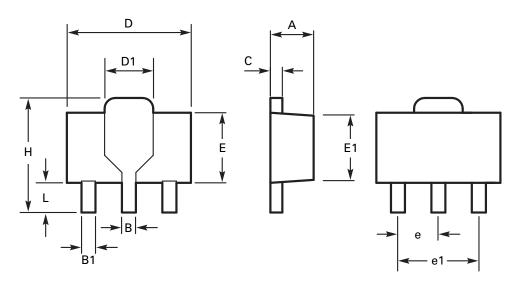


Normalized Thermal Transient Impedance, Junction-to-Foot

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Package outline - SOT89



DIM	Millin	neters	Inc	nches DIM Millimeters Inch		Millimeters		hes	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	1.40	1.60	0.550	0.630	Е	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118 BSC	
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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